



Material Content Data Sheet



Sales Product Name	TLE4964-2M			Issued	19. January 2018			
MA#	MA001228030							
Package	PG-SOT23-3-15			Weight*	9.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35595	35595
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365592	367133
	noble metal	gold	7440-57-5	0.019	0.19	0.19	1890	1890
	encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5463
encapsulation	plastics	epoxy resin	-	1.153	11.75		117454	
	inorganic material	silicondioxide	60676-86-0	4.157	42.33	54.63	423381	546298
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15240	15240
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15133	15133
glue	plastics	epoxy resin	-	0.032	0.33		3274	
	noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18711
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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